

PART INFORMATION	
Mfg Item Number	MPXAZ6115AC6T1
Mfg Item Name	SMOUTLN SMT W/AXIAL PORT
SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2016-03-17
Response Document ID	0882K50010S288A1.21
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com
DECLARATION	
EU RoHS	Yes
Pb Free	No
HalogenFree	No
Plating Indicator	
EU RoHS Exemption(s)	7c-I
MANUFACTURING	
Mfg Item Number	MPXAZ6115AC6T1
Mfg Item Name	SMOUTLN SMT W/AXIAL PORT
Version	ALL
Weight	1.333700
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	245 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.0021						g					
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Silicone gum	67762-04-1		0.00002168	g	10324	1.0324		16	0.0016
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and Silicones, di-Me, Me vinyl, vinyl group-terminated	68083-18-1		0.00025811	g	122911	12.2911		193	0.0193
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2		0.00082595	g	383313	38.3313		619	0.0619
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-		0.0004646	g	221236	22.1236		348	0.0348
Non-Conductive Epoxy/Adhesive		Glass	D4 and HMDZ treated Silicon Dioxide	68937-51-9		0.00030974	g	147493	14.7493		232	0.0232
Non-Conductive Epoxy/Adhesive		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.00019617	g	93412	9.3412		147	0.0147
Non-Conductive Epoxy/Adhesive		Metals	Titanium (IV) Oxide	13463-67-7		0.00002375	g	11308	1.1308		17	0.0017
Part	0.2535						g					
Part		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0		0.002535	g	10000	1		1900	0.19
Part		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.002535	g	10000	1		1900	0.19
Part		Plastics/polymers	Polybutylene terephthalate (PBT)	30965-26-5		0.11154	g	440000	44		83632	8.3632
Part		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6		0.0849225	g	335000	33.5		63674	6.3674
Part		Glass	Fibrous-glass-wool	65997-17-3		0.0519675	g	205000	20.5		38964	3.8964
Copper Lead Frame	0.7929						g					
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.4373673	g	551592	55.1592		327949	32.7949
Copper Lead Frame		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.01678886	g	21174	2.1174		12558	1.2558
Copper Lead Frame		Metals	Gold, metal	7440-67-5		0.00062718	g	791	0.0791		470	0.047
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.0003687	g	465	0.0465		276	0.0276
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.0105424	g	13296	1.3296		7904	0.7904
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.00659931	g	8323	0.8323		4948	0.4948
Copper Lead Frame		Metals	Palladium, metal	7440-05-3		0.0003235	g	408	0.0408		242	0.0242
Copper Lead Frame		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6		0.10086868	g	127341	12.7341		75705	7.5705
Copper Lead Frame		Glass	Fibrous-glass-wool	65997-17-3		0.21876428	g	275904	27.5904		164028	16.4028
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.00055979	g	706	0.0706		419	0.0419
Bonding Agent	0.0212						g					
Bonding Agent		Metals	Proprietary Material-Other aluminum compounds	-		0.00954	g	450000	45		7153	0.7153
Bonding Agent		Solvents, additives, and other materials	Other guanidine compounds	-		0.00053	g	25000	2.5		397	0.0397
Bonding Agent		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00053	g	25000	2.5		397	0.0397
Bonding Agent		Plastics/polymers	Other phenolic resins	-		0.0106	g	500000	50		7947	0.7947
Pb Glass Frit Semiconductor Di	0.0112				7c-I		g					
Pb Glass Frit Semiconductor Di		Lead/Lead Compounds	Lead (II) titanate	12060-00-3		0.00011627	g	10381	1.0381		87	0.0087
Pb Glass Frit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3		0.00011136	g	9943	0.9943		83	0.0083
Pb Glass Frit Semiconductor Di		Solvents, additives, and other materials	2,2,4,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4		0.00011136	g	9943	0.9943		83	0.0083
Pb Glass Frit Semiconductor Di		Glass	Silicon, doped	-		0.01086101	g	969733	96.9733		8143	0.8143
Gel Die Encapsulant	0.028						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Fluorosilicone monomer (fluorosilicone rubber)	2374-14-3		0.02184	g	780000	78		16375	1.6375
Gel Die Encapsulant		Plastics/polymers	Oxetane, 2,2,3,3-tetrafluoro-homopolymer, fluorinated	113114-19-5		0.00616	g	220000	22		4618	0.4618
Gel Die Encapsulant	0.028						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Fluorosilicone monomer (fluorosilicone rubber)	2374-14-3		0.02184	g	780000	78		16375	1.6375
Gel Die Encapsulant		Plastics/polymers	Oxetane, 2,2,3,3-tetrafluoro-homopolymer, fluorinated	113114-19-5		0.00616	g	220000	22		4618	0.4618
Bonding Wire	0.001						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.001	g	1000000	100		749	0.0749
Cap/Cover	0.1958						g					
Cap/Cover		Metals	Chromium, metal	7440-47-3		0.03608007	g	184270	18.427		27052	2.7052
Cap/Cover		Metals	Copper, metal	7440-50-8		0.00049028	g	2504	0.2504		367	0.0367
Cap/Cover		Solvents, additives, and other materials	Sulfur	7704-34-9		0.00000979	g	50	0.005		7	0.0007
Cap/Cover		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00003427	g	175	0.0175		25	0.0025
Cap/Cover		Solvents, additives, and other materials	Silicon	7440-21-3		0.00098037	g	5007	0.5007		735	0.0735
Cap/Cover		Metals	Iron, metal	7439-89-6		0.13918971	g	710877	71.0877		104363	10.4363
Cap/Cover		Metals	Manganese, metal	7439-96-5		0.00225503	g	11517	1.1517		1690	0.169
Cap/Cover		Nickel (external applications only)	Nickel	7440-02-0		0.01647128	g	84123	8.4123		12350	1.235
Cap/Cover		Metals	Titanium, metal	7440-32-6		0.000196	g	1001	0.1001		146	0.0146
Cap/Cover		Solvents, additives, and other materials	Carbon	7440-44-0		0.0000932	g	476	0.0476		69	0.0069

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPXAZ6115AC6T1_IPC1752_v11.xml

http://www.freescale.com/mcds/MPXAZ6115AC6T1_IPC1752A.xml